DP83TC812, DP83TC813, and DP83TC814: Configuring for Open Alliance Specification Compliance



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ABSTRACT

Open Alliance (OA) mandates different tests for 100Base-T1 PHY. This document describes the procedure to put the DP83TC812, DP83TC813, and DP83TC814 (hereafter referred to as *DP83TC81x*) devices in the required test mode to carry out different Open Alliance tests.

The software and hardware configuration used during the testing of the DP83TC81x is found in this document. This configuration has been tested across different OA compliance houses: UNH, FTZ, and C&S and should be treated as a minimum requirement. Further improvement based on the system use-case of the customer is possible with additional hardware and software configuration.

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Introduction www.ti.com

1 Introduction

The DP83TC81x was evaluated in accordance with the following OPEN Alliance (OA) specifications:

- OPEN Alliance 100BASE-T1 EMC Test Specification for Transceivers Revision 2.0, by FTZ Zwickau
- OPEN Alliance 100BASE-T1 Interoperability Test Suite v1.0, by C&S Group, GmbH
- OPEN Alliance 100BASE-T1 test specifications for Physical Coding Sublayer (v. 1.0), PHY Control (v. 1.0), and Physical Media Attachment (v. 1.2) by the University of New Hampshire (UNH) Inter-Operability Lab.

This application note provides the details of unique hardware and software configuration used for all of the previously-listed tests.

Document also provides the required procedure details for these tests and this should assist customers implementing corresponding ECU level tests.



2 Hardware Configuration

2.1 Schematic

Schematics and the right components for MDI, reference clock, and power network are critical for the performance of 100Base-T1 PHY. This section captures the recommended schematics and component values used during OA TC-1 testing. For TC10 operation, the wake pin must be pulled to a logic high state.

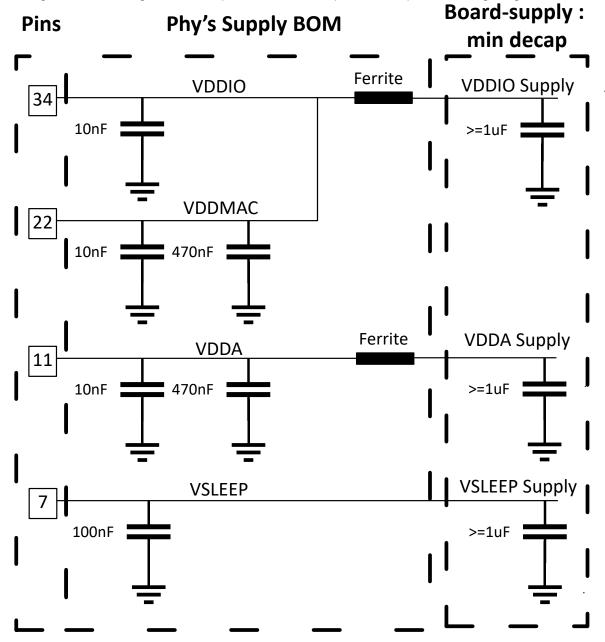


Figure 2-1. Power Supply Network: For Applications With Sleep Mode Requirement (DP83TC812)



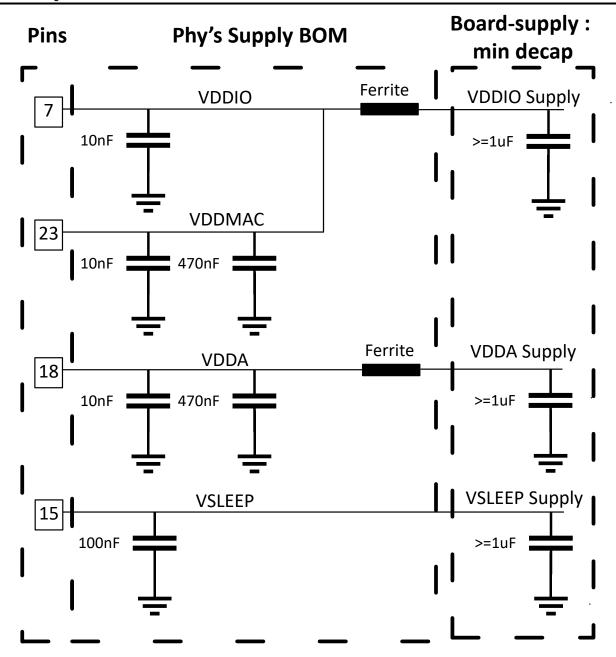


Figure 2-2. Power Supply Network: For Applications With Sleep Mode Requirement (DP83TC813)



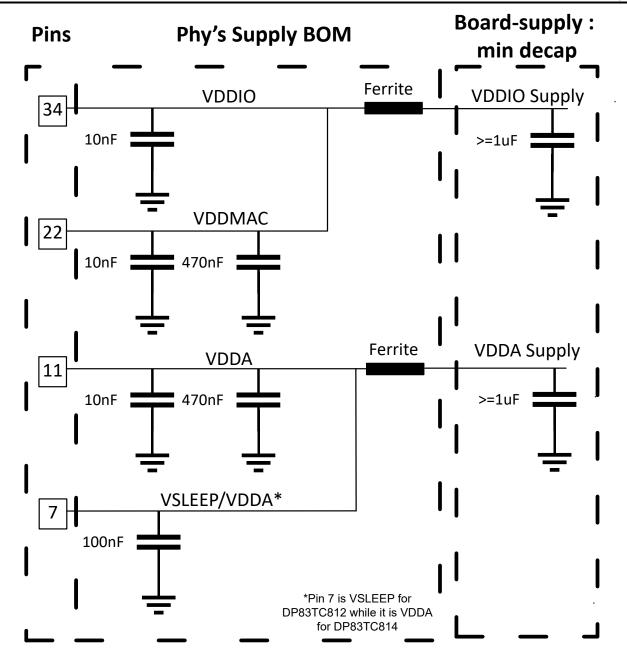


Figure 2-3. Power Supply Network: For Applications Without Sleep Mode Requirement (DP83TC812 and DP83TC814)



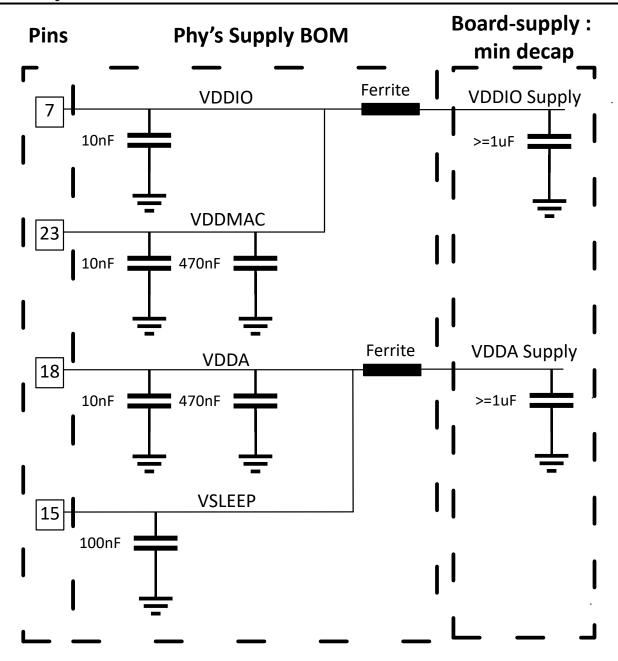


Figure 2-4. Power Supply Network: For Applications Without Sleep Mode Requirement (DP83TC813)

www.ti.com Hardware Configuration

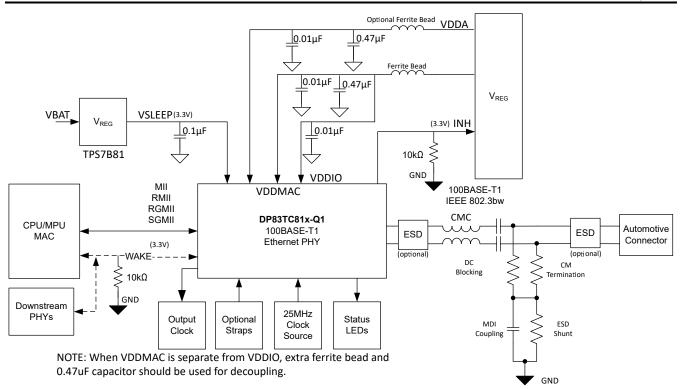


Figure 2-5. Typical TC-10 Application With Peripheral (DP83TC812 and DP83TC813)

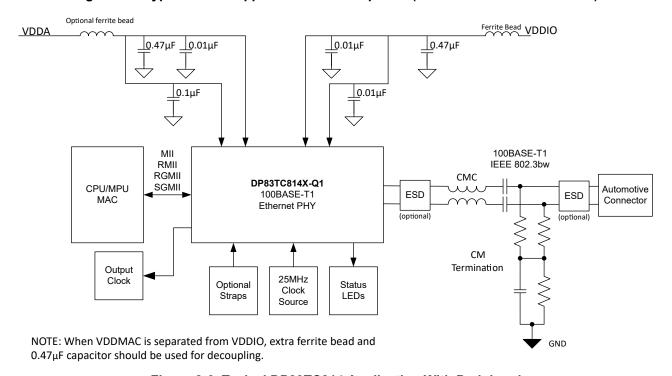


Figure 2-6. Typical DP83TC814 Application With Peripheral



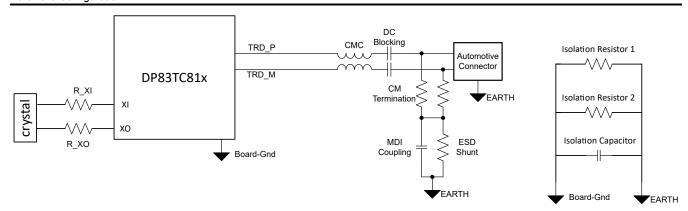


Figure 2-7. MDI and Crystal Schematic

Table 2-1. Parameters, Components, and Values

PARAMETER COMPONENT	VALUE
V _{DDIO} V _{DDMAC}	1.8 V, 2.5 V, or 3.3 V
De-Coupling Capacitors V _{DDIO}	10 nF
De-Coupling Capacitors V _{DDMAC}	10 nF, 470 nF
Combined Ferrite Bead for V _{DDIO} V _{DDMAC} ¹	BLM18KG601SH1
V_{DDA}	3.3 V
De-Coupling Capacitors V _{DDA}	10 nF, 470 nF
(Optional): Ferrite Bead for V _{DDA}	BLM18KG601SH1
V_{sleep}	3.3 V
De-Coupling Capacitors V _{sleep}	0.1 μF
DC Blocking Capacitors (1% accurate, 100 V)	0.1 µF
Common-Mode Choke	DLW43MH201XK2L, DLW32MH201XK2, AE2002, ACT1210L-201
Common-Mode Termination Resistors (1% accurate, 0.75 W, Size: 2010)	1 kΩ
MDI Coupling Capacitor	4.7 nF
ESD Shunt (5% accurate, 0.125 W, Size: 0805	100 kΩ
Isolation Resistor 1 (0.25 W, Size: 1206)	0 Ω
Isolation Resistor 2 (0.25 W, Size: 1206)	0 Ω
Isolation Capacitor	Not populated
R_XI	100 Ω
R_XO	Minimum required for crystal wattage specification
ESD (Optional)	ESD Devices qualified by "Open Alliance 100BASE-T1 EMC Test Specification for ESD suppression devices" with load capacitance < 5 pF can be used

If V_{DDIO} is separate from V_{DDMAC} , then additional ferrite bead and a 0.47- μ F capacitor are required on V_{DDIO} . This ferrite bead has the same component number: BLM18KG601SH1.

www.ti.com Software Configuration

3 Software Configuration

This section contains the register settings of DP83TC81x used during tests in different OA compliance test houses. These settings are recommended as the minimum requirement. Further parameters are available to be programmed if required by system- or board-level constraints. The default values listed are read upon power up or hard reset of the device.

The PHY supports bootstrap option to configure in Autonomous or Managed mode and it is in Autonomous mode by default. Managed mode strap option is recommended to prevent the link-up process from initiating while the software configuration from Table 3-1 and Table 3-2 is being executed. Once the software configuration is completed, the PHY can be removed from Managed mode by setting bit 0x18B[6] to '0'.

Table 3-1. Master Mode Configuration

MMD	REGISTER	DEFAULT	OPTIMIZED	DESCRIPTION
1f	x001f	x0000	x8000	Hard reset
1f	x0523	x0000	x0001	To disable link-up start until configuration is complete
01	x0834	xC000 or x8000	xC001	To configure PHY in Master mode
1f	x081C	x00E2	x0FE2	Configuration to enable shorter linkup time
1f	x0872	x00C0	x0300	Configuration to enable shorter linkup time
1f	x0879	x000F	x0F00	Configuration to enable shorter linkup time
1f	x0806	x2929	x2952	Configuration to enable shorter linkup time
1f	x0807	x3333	x3361	Configuration to enable shorter linkup time
1f	x0808	x3D3D	x3D7B	Configuration to enable shorter linkup time
1f	x083E	x0445	x045F	Configuration to enable shorter linkup time
1f	x0834	xC000 or x8000	x8000	Configuration to enable shorter linkup time
1f	x0862	x01F8	x00E8	Configuration to enable shorter linkup time
1f	x0896	x22CB	x32CB	Configuration to enable shorter linkup time
1f	x003E	x0001	x0009	Configuration to enable shorter linkup time
1f	x001F	x0000	x4000	Soft reset
1f	x0523	x0000	x0000	Enable link-up start after end of configuration

Table 3-2. Slave Mode Configuration

Table 3-2. Slave Mode Configuration					
MMD	REGISTER	DEFAULT	OPTIMIZED	DESCRIPTION	
1f	x001f	x0000	x8000	Hard reset	
1f	x0523	x0000	x0001	To disable link-up start until configuration is complete	
01	x0834	x8000/xC000	x8001	To configure PHY in Slave mode	
1f	x0873	x0921	x0821	Configuration to enable shorter linkup time	
1f	x0896	x22CB	x22FF	Configuration to enable shorter linkup time	
1f	x089E	x0492	x0000	Configuration to enable shorter linkup time	
1f	x001F	x0000	x4000	Soft reset	
1f	x0523	x0000	x0000	Enable link-up start after end of configuration	

Testing PMA Www.ti.com

4 Testing PMA

OA TC-1 specifies different electrical tests for the front end of the 100Base-T1 PHY. Different test modes have been specified in the standard document. In each test mode, PHY is supposed to generate patterns on MDI lines or expose internal clock signal on a pin for measurement of different electrical parameters.

DP83TC81x supports all these test modes. This section gives details of the required configuration to enter into each test mode.

A detailed PMA test report from UNH (OA compliance test house) with OA- and IEEE-compliant results is available on request.

4.1 PMA Testing Procedure

Note

- Before programming any of the test modes, DP83TC81x should be loaded with the respective initialization register configuration (master or slave) as described in Section 3.
- Test mode 1 requires the link to be established between DUT and link-partner, hence register [0x1] should read as 0x65 before running the test.

Table 4-1. Programming PMA Test Modes

Table 4 1.1 Togramming I MA Test Modes				
TEST MODE	MMD	REGISTER	<u>VALUE</u>	
Test Mode 1	x01	0x0836	0x2000	
Test Mode 2	x01	0x0836	0x4000	
Test Mode 4: Tx_Tclk 25	x01	0x0836	0x8000	
MHz on the CLKOUT pin.	x01	0x045F	0x000D (DP83TC812, DP83TC814) 0x0007 (DP83TC813)	
Test Mode 5	x01	0x0836	0xA000	



5 Testing IOP: Link-up and Link-down

OA TC-1 specifies different PHY level tests to test link-up time, link-down time, and link stability. This section highlights the test sequence used for these IOP tests for PHY-level testing and the same can be ported for ECU level tests.

TC-1 interoperability tests are carried out by OA compliance test house C&S. To test interoperability of DP83TC81x, C&S tests each of these parameters with DP83TC81x and other 100Base-T1 certified PHYs as its link-partners. Each of these parameters are tested for a large number of iterations over different temperatures and cable lengths.

A detailed IOP test report from C&S with OA compliant results is available on request.

5.1 IOP Testing Procedure

Use the following IOP testing procedure:

· Start of measurement:

For the IOP tests measuring link-up time either after power-up or after hardware reset, it is important to start the measurement of link-up time after the initialization configuration is loaded back into DP83TC81x. As the configuration is loaded into the PHY by a controller, we recommend the controller to give an indication (a software bit or an IO state) after the last configuration register is written. This indicator going high is the start of measurement of link-up time.

Status to be polled:

Link-status is indicated by bit 2 of register 0x1: 1 = link-up; 0 = link-down. This should be polled to indicate the event of link-up or link-down during these tests.

Note

- If system desires no automatic link-up after power-up (link to only happen after writing the initialization script), managed mode of DP83TC81x should be used by using strap on pin LED 1.
- The PHY supports the bootstrap option to configure in Autonomous or Managed mode and it is
 in Autonomous mode by default. Managed mode strap option is recommended to prevent the link
 up process from initiating while the software configuration is being executed. Once the software
 configuration is completed, the PHY can be removed from Managed mode by setting bit 0x18B[6]
 to '0'.

Testing SQI www.ti.com

6 Testing SQI

SQI gives the indication of signal quality on the copper cable.

OA TC-1 indicates that SQI values should decrease monotonically with increase in noise levels.

A detailed SQI test report from C&S with OA compliant results is available on request.

6.1 SQI Value Interpretation

Register bits 0x871[3:1] contain the SQI value. This register can be polled to understand the appropriate range of MSE values for each SQI value.

Table 6-1. SQI Values for Register Bits 0x871[3:1]

0x871 [3:1]	OPEN ALLIANCE SQI	MSE VALUES
0x0	SQI = 0 (Worst)	MSE > 133
0x1	SQI = 1	11 < MSE ≤ 133
0x2	SQI = 2	7 < MSE ≤ 11
0x3	SQI = 3	5 < MSE ≤ 7
0x4	SQI = 4	4 < MSE ≤ 5
0x5	SQI = 5	3 < MSE ≤4
0x6	SQI = 6	2 < MSE ≤ 3
0x7	SQI = 7 (Best)	MSE ≤ 2

www.ti.com Testing TDR

7 Testing TDR

This section describes the procedure to test cable faults: open or short.

A detailed TDR test report from C&S with OA-compliant results is available on request.

Note

OA TC-1 tests done at C&S tests are for open and short cable fault test cases. Also TDR is usually run to find the root-cause when there is no link. The test procedure described in Section 7.1 has an extra step over the compliance test procedure: to force link-down condition when possible (use if required).

7.1 TDR Testing Procedure

Table 7-1. TDR Run Procedure

SEQUENCE	DESCRIPTION	REGISTER READ/WRITE
Step 1: For DP83TC81x as master	Force the link-down by writing register and enable link-partner to go silent. Wait for about 1 s after register write. In case of valid open and short cable faults, TDR still works fine without step 1. For good cable case, TDR register 0x001E may show <i>Fail</i> on bypassing this step.	Reg[0x1834] = 0xC001
Step 1: For DP83TC81x as slave	Force the link-down by writing register and enable link-partner to go silent. Wait for about 1 s after register write. In case of valid open and short cable faults, TDR still works fine without step 1. For good cable case, TDR register 0x001E may show <i>Fail</i> on bypassing this step.	Reg[0x1834] = 0x8001
Step 2	TDR configuration: Pre-run	Reg[0x0523] = 0x0001 //Transmit disable Reg[0x0827] = 0x4800 Reg[0x0301] = 0x1701 Reg[0x0303] = 0x023D Reg[0x0305] = 0x0015 Reg[0x0306(4)] = 1 //Detect half wire open Reg[0x001F] = 0x4000 Reg[0x0523] = 0x0000 //Transmit enable Reg[0x001F] = 0x0000
Step 3	Start TDR	Reg[0x001E(15)] = 1
Step 4	Wait for 100 ms (should be sufficient for TDR to converge for maximum cable length)	
Step 5	Read 0x001E[1:0] = [TDR done : TDR fail]. Value should be [1,0]. Fault type and locations are valid only if this correct value is read. Value other than [1,0] means that there is some noise on the line which is causing TDR to fail.	



Testing TDR Www.ti.com

Table 7-1. TDR Run Procedure (continued)

SEQUENCE	DESCRIPTION	RE	REGISTER READ/WRITE	
Step 6	Fault type and location is read.	For fault types:	0 for fault status and fault type. 0x0310[8] = half_open_detect	
		0b	Half wire open not detected	
		1b	Half wire open detected	
		TDR_TC-1 Reg	0x0310[7] = peak_detect	
		0b	Fault not detected	
		1b	Fault detected	
		TDR_TC-1 Reg	0x0310[6] = peak_sign	
		0b	short	
		1b	open	
		If a valid fault det	valid if Fault detected in cable ected: register the fault location in meters.	

www.ti.com Testing EMC and EMI

8 Testing EMC and EMI

OA TC-1 specifies conducted EMC and EMI tests. For DP83TC81x, these tests were carried out in OA compliance test house FTZ and testing of emissions on MDI, emissions on each supply pin, immunity to RF signals are part of the test suite. The board was designed in accordance with OA specifications by FTZ.

Hardware and software configurations highlighted in the document were used for these conducted EMC and EMI tests. Configurations are available if further enhancement over TC-1 specs are required for an application.

A detailed test report from FTZ with procedures and OA-compliant results is available on request.

Other than conducted emission tests (for OA TC-1 compliance), DP83TC81x (with mentioned hardware and software configuration) has been tested against different radiated emission and radiated immunity requirements of different OEMs. Details of radiated emission and immunity test results are available on request. Configurations are available if further enhancement of margins is required for an application.

9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

C	hanges from Revision * (December 2021) to Revision A (May 2022)	Page
•	Added support for DP83TC813, DP83TC814 devices throughout the document	1
•	Added description of ESD component to Parameters, Components, and Values. Added optional notice for	or
	VDDA decoupling capacitor. Updated ferrite bead recommendation for VDDIO or VDDMAC. Added footr	note
	for VDDIO and VDDMAC ferrite bead. Modified figures to include pertinent information relating to	
	DP83TC813 and DP83TC814	3
•	Added Power Supply Network: For Applications With Sleep Mode Requirement (DP83TC813), Power Supply Network:	upply
	Network: For Applications Without Sleep Mode Requirement, Typical DP83TC814 Application with Perip	heral
	figures	3
	Lindated Test Mode 4 command for DP83TC813	10

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